

ELDRE COMPONENTS, INC.

1239 University Ave.

Rochester, N. Y. 14607

USE THIS INVITATION
TO GET YOUR FREE TICKET
TO NEP/CON '66—WORTH \$4.00



WE WOULD LIKE YOU TO BE OUR GUEST AT NEP/CON '66

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This invitation, when properly filled out, and mailed to Nep/Con headquarters, will bring you — free — a *Complimentary Ticket* admitting you to the exhibit floor all three days of NEP/CON '66. If you wish to attend the Technical Sessions, your Complimentary Ticket will entitle you to a \$4.00 discount on the price.

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The Fourth Annual
**NATIONAL ELECTRONIC
PACKAGING/PRODUCTION
CONFERENCE**
June 21-22-23, 1966
New York Coliseum
New York City, N. Y.

TECHNICAL SESSIONS PROGRAM

THERMAL DESIGN IN ELECTRONIC EQUIPMENT • INTERCOMPONENT CONNECTION IN ELECTRONIC PACKAGING • ELECTRONIC PACKAGING WITH THIN-FILM CIRCUITS • ADVANCED MANUFACTURING TECHNIQUES • SHIPBOARD AND UNDERWATER EQUIPMENT PACKAGING • INTERCIRCUIT CONNECTIONS IN ELECTRONIC EQUIPMENT • MATERIALS IN ELECTRONIC PACKAGING • NEW TECHNIQUES IN P.C. AND MULTILAYER DESIGN AND MANUFACTURE • DESIGNING PACKAGES AND ASSEMBLIES FOR SHOCK AND VIBRATION RESISTANCE • AIRBORNE AND SPACEBORNE EQUIPMENT PACKAGING • MINIATURE STRUCTURES AND ASSEMBLIES • QUALITY CONTROL/RELIABILITY IN ELECTRONIC PACKAGING

—total of 60 state-of-the-art papers!

SPECIALIZED WORKSHOP PROGRAM

THIN-FILM SERIES

EVAPORATION TECHNIQUES FOR MANUFACTURING THIN-FILM CIRCUITS AND COMPONENTS • SPUTTERING TECHNIQUES FOR MANUFACTURING THIN-FILM CIRCUITS AND COMPONENTS • CHEMICAL VAPOR DEPOSITION TECHNIQUES FOR MANUFACTURING THIN-FILM CIRCUITS AND COMPONENTS.

HIGH VOLUME PRODUCTION OF ELECTRONIC EQUIPMENT SERIES

LOW-COST PRODUCTION OF PRINTED CIRCUITS • AUTOMATING THE PRODUCTION ASSEMBLY PROCESS • MICROSOLDERING AND MICRO-WELDING

PACKAGING/PRODUCTION OF HIGH DENSITY ELECTRONIC ASSEMBLIES

MINIATURE COMPUTER PACKAGING • THERMAL DESIGN OF HIGH DENSITY PACKAGES • HOW TO ACHIEVE ZERO DEFECTS IN PRODUCTION

—over 75 expert panelists!

SOCIAL EVENTS

Annual Awards Banquet and Reception . . . Entertaining Ladies' Program . . . bring your wife and make NEP/CON '66 a 3-day holiday, as well as the most important professional event of the year!

EXHIBITS

Over 250 manufacturers will exhibit thousands of new packaging/production products, many of them for the first time anywhere. One single idea discovered at NEP/CON can save your company thousands of dollars *this year!*

HOURS

TECHNICAL SESSIONS:
8:30 AM to 12:00 noon

WORKSHOPS:
3:00 PM to 6:00 PM

EXHIBITS:
12:00 noon to 6:00 PM

ACT TODAY!
**SEND FOR YOUR FREE
ADMISSION BADGE —**
(no obligation)

*Hundreds of exhibits —
thousands of new
packaging/production ideas.*

Fill out — detach — and mail this form to obtain your **FREE** admission badge.

ADMISSIONS COMMITTEE — NEP/CON '66
222 WEST ADAMS STREET, CHICAGO, ILLINOIS 60606

Gentlemen:

I have been invited to attend NEP/CON '66 as the guest of one of the exhibitors. Please send me my free admission badge to the exhibit floor, and a copy of the technical program, together with information on the technical papers sessions, workshops, banquet, and hotel reservations. I understand that there is no obligation involved in requesting this information.

IMPORTANT NOTE

DO NOT mail this card after June 10, 1966! Instead, fill out this form, and bring it to the registration booth at the conference, where it will be exchanged for a free admission badge to the exhibit floor, or credited against your admission fee to the technical or workshop sessions of your choice.

- ☐ I certify that I am engaged in packaging/production activities.
- ☐ I supervise _____ people.
- ☐ Please send me _____ additional complimentary ticket applications for other engineers in my department.

Name _____
(please print)

Title _____

Company _____

Address _____

City _____ State _____

I understand that admission badges and tickets are not transferable.